Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.0075 x .0075”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .0075” X .0075”**

**Backside Potential: CATHODE**

**Mask Ref: CPZ18**

**APPROVED BY: DK DIE SIZE .0135” X .0135” DATE: 11/13/17**

**MFG: CENTRAL THICKNESS .0075” P/N: CMPZ5231B**

**DG 10.1.2**

#### Rev B, 7/1